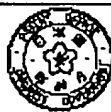




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(71) Applicant: FUJI PHOTO FILM CO LTD

(72) Inventor: TAN SHIRO

(54) POSITIVE TYPE RADIATION SENSITIVE  
RESIN COMPOSITION

## (57) Abstract:

**PROBLEM TO BE SOLVED:** To provide a positive type radiation sensitive resin composition which improves line edge roughness (LER), has high sensitivity and high resolving power and ensures improved surface roughness of a resist pattern.

**SOLUTION:** The positive type radiation sensitive composition contains at least (a) a resin having, which is decomposed by the action of an acid increases solubility in an alkali developing solution, a compound which generates the acid when irradiated with active light or radiation, (c) an organic carboxylic acid compound, (d) a basic compound and (e) a solvent.

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